

(0.635 mm) .025"

MIT SERIES

MIXED TECHNOLOGY HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIT

Insulator Material:

Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over 50 μm (1.27 μm) Ni

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating:

275 VAC

Max Cycles:

100

RoHS Compliant:

Yes

Board Mates:

MIS

Standoffs:

SO

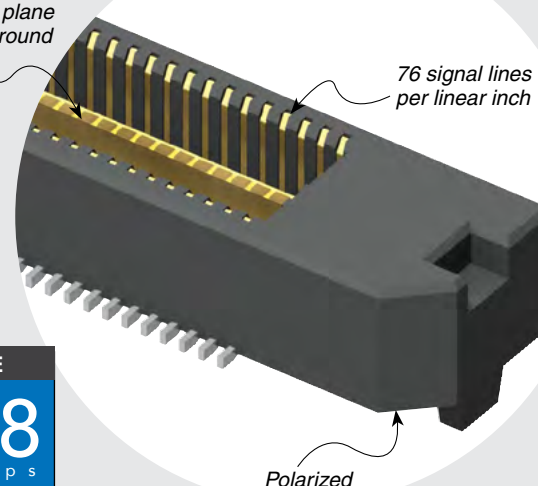


• Mixed technology footprint

Integral metal plane for power or ground

76 signal lines per linear inch

Choice of mated heights



Polarized

HIGH-SPEED CHANNEL PERFORMANCE

MIT/MIS @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

28 Gbps

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (019-057)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

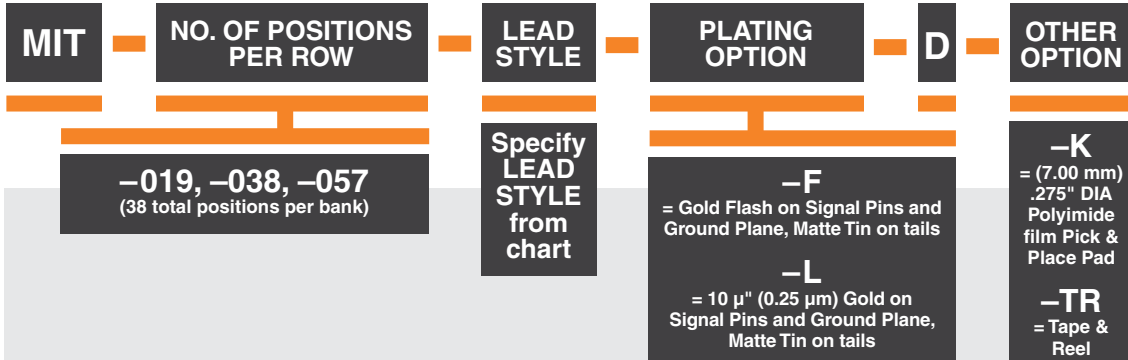


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ALSO AVAILABLE (MOQ Required)

- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μm (0.76 μm) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

Contact Samtec.



MIT — **NO. OF POSITIONS PER ROW** — **LEAD STYLE** — **PLATING OPTION** — **D** — **OTHER OPTION**

-019, -038, -057
(38 total positions per bank)

Specify **LEAD STYLE** from chart

-F
= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

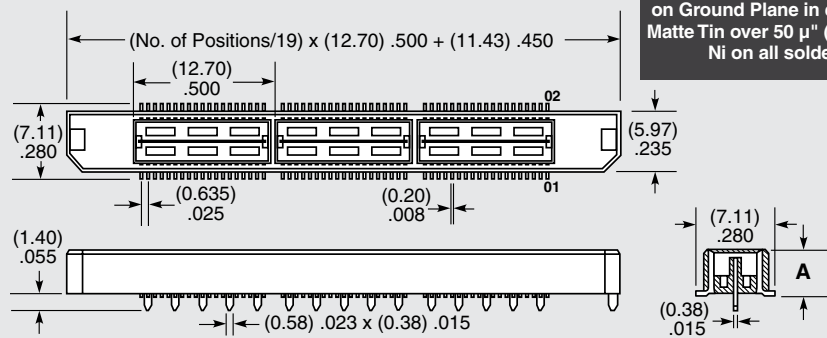
-L
= 10 μm (0.25 μm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

-C*
= Electro-Polished Selective 50 μm (1.27 μm) min Au over 150 μm (3.81 μm) Ni on Signal Pins in contact area, 10 μm (0.25 μm) min Au over 50 μm (1.27 μm) Ni on Ground Plane in contact area, Matte Tin over 50 μm (1.27 μm) min Ni on all solder tails

-K
= (7.00 mm) .275" DIA Polyimide film Pick & Place Pad

-TR
= Tape & Reel

LEAD STYLE	A
-01	(4.27) .168
-02	(7.26) .286



MIS LEAD STYLE	MATED HEIGHT*	
	MIT LEAD STYLE -01	-02
-01	(5.00) .197	(8.00) .315

*Processing conditions will affect mated height. See SO Series for board space tolerances.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.